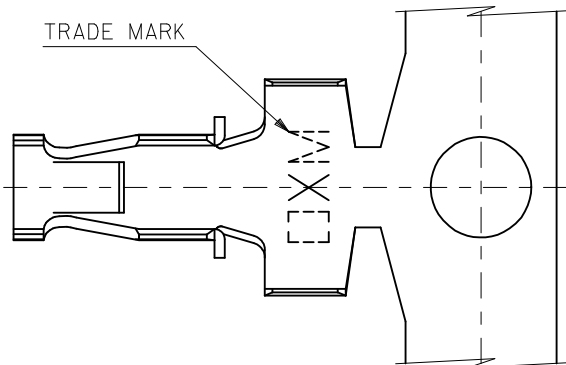
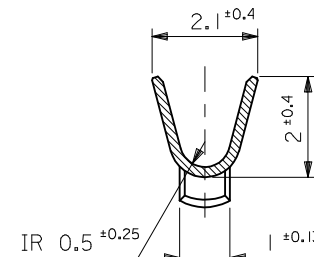
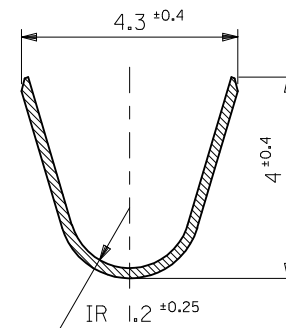


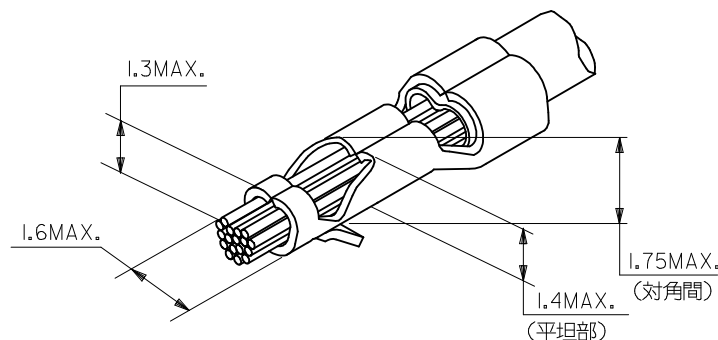
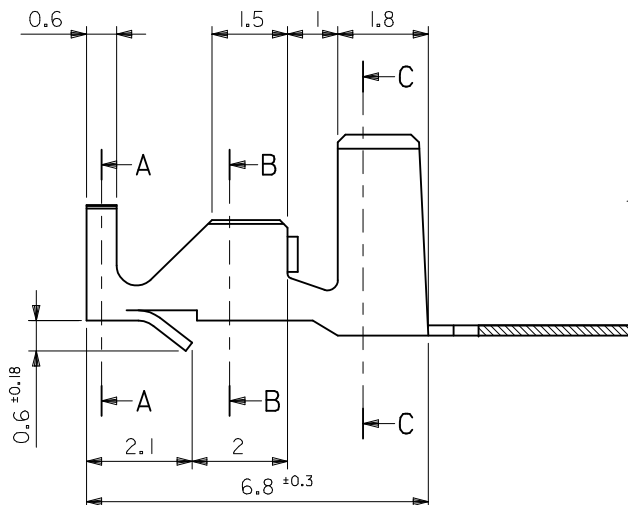
SECT. A-A



SECT. B-B



SECT. C-C



圧着外観図
OUTSIDE VIEW OF CRIMP

NOTES

- 推奨プリント基板穴径: $\phi 1.8^{+0.1}_{-0}$
RECOMMENDED P.C.B. HOLES: $\phi 1.8^{+0.1}_{-0}$
- 推奨プリント基板厚: $t1.57^{+0.2}_{-0}$
RECOMMENDED P.C.B. THICKNESS: $1.57^{+0.2}_{-0}$
- 材料の厚み: 0.203
MATERIAL THICKNESS: 0.203

TIN-LEAD(90-10) 3.8 μm MIN. OVER NICKEL 1.3 μm MIN.	PHOSPHOR BRONZE	CHAIN	39-00-0277	5298PBPT
TIN 0.9 μm MIN. REFLOW TREATMENT (PRE-PLATED)	PHOSPHOR BRONZE	CHAIN	39-00-0230	5298PBT
TIN 0.9 μm MIN. OVER COPPER 0.5 μm MIN. (PRE-PLATED)	BRASS	CHAIN	08-70-0106	5298T
PLATING	MATERIAL	FORM	EDP NO.	ENG. NO.

材料 MATERIAL	SEE TABLE & NOTE
仕上げ FINISH	— # —
適用電線範囲 WIRE RANGE	AWG #18-22
被覆外径 INS. RANGE	$\phi 1.7-3.05$

REVISED	EC NO. J2017-0224	2016/10/12
	DRWN: NISHIKAWA	2016/10/12
	CHKD: TAKAHASHI	2016/10/12
	APPR: MASAO	2016/10/14

GENERAL TOLERANCES (UNLESS SPECIFIED)			
0.25 UNDER	±	0.25 OVER	±
0.5 UNDER	±	0.5 OVER	±
1.0 UNDER	±	1.0 OVER	±
10 UNDER	±0.2	10 OVER	±0.25
30 UNDER	±0.3	30 OVER	±0.3
ANGULAR	±3 °		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			

DIMENSION STYLE MM ONLY	
DRAWN BY	DATE
H. HIRAMOTO	'91/09/05
CHECKED BY	DATE
H. HIRAMOTO	'93/07/06
APPROVED BY	DATE
M. FUKUSHIMA	'93/07/06
MATERIAL NO.	
SEE TABLE	

SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
TITLE		
LOW PROFILE PC BOARD CRIMP PIN		
moLEX		
DOCUMENT NO.		SHEET NO.
SD-5298-001		1 OF 1
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